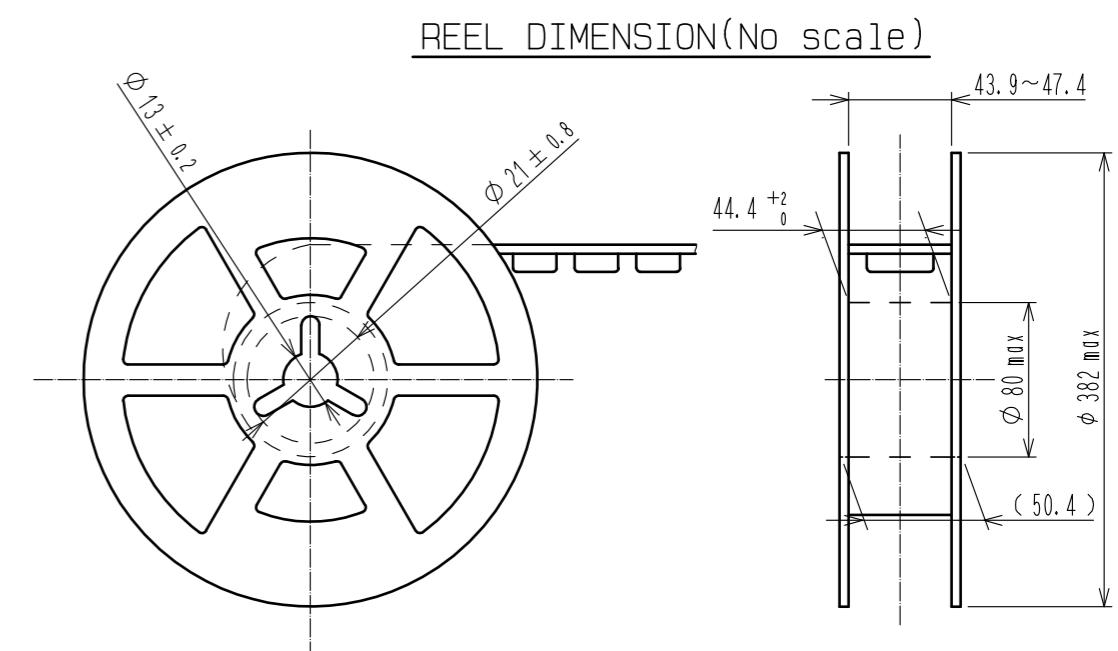
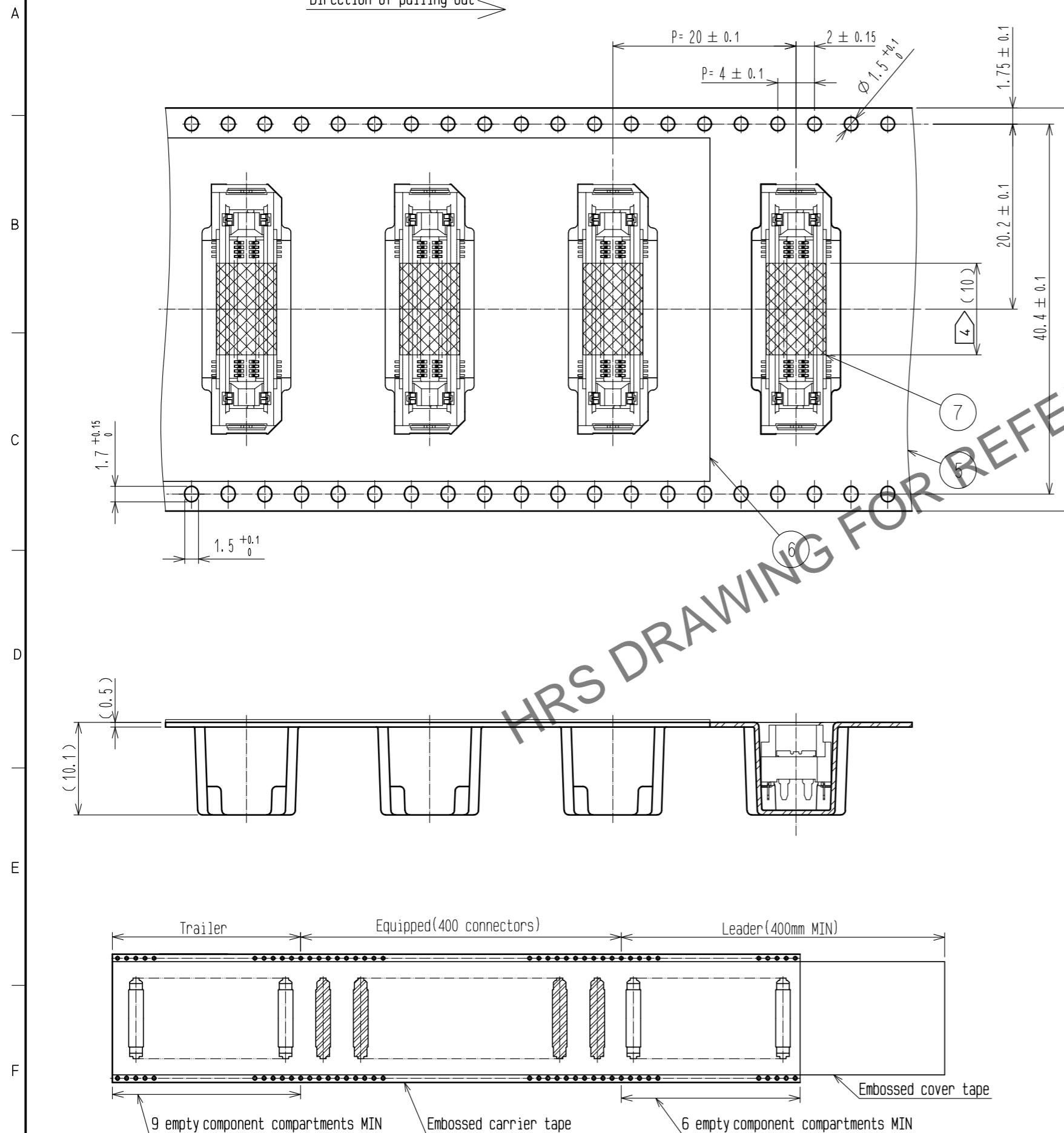


2> DRAWING FOR PACKING(2:1)

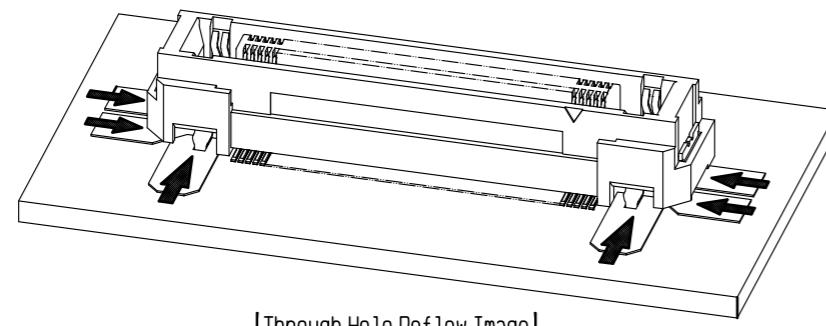
Direction of pulling out



In order to prevent any potential failures with the connector, please read the following below:

### | Through Hole Reflow Process |

FX23 and FX23L Series use through hole reflow process, where power contacts/metal fittings draw solder paste from the surrounding area. In regards to the soldering paste print area, the surface shall be flat with no exposed copper surface. If the surface is not flat, power contacts/metal fittings may not properly draw the soldering paste, resulting insufficient solder on the power contacts/metal fittings as well as ball-shaped solder on the PCB.



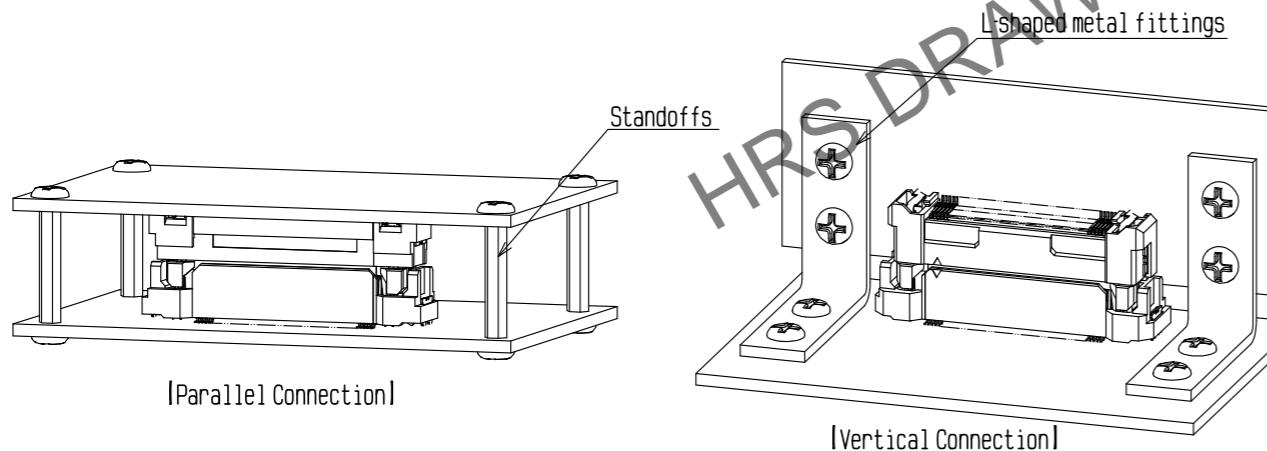
| Through Hole Reflow Image |

When applying solder from the opposite side of the PCB, due to the unavailability in solder space on the mounting side, there may be a case where solder is insufficiently applied to power contacts/metal fittings. Please check if the power contacts/metal fittings are properly soldered when doing so.

### | Board Stabilization |

This connector can absorb misalignment of boards but cannot absorb vibration itself. When boards are supported by a connector only, the connector will be loaded excessively, which may result in a damage or contact failure.

Take measures to secure boards with an object other than connector as shown in the following figure.



Note that when a spacer is installed far from connectors, incomplete mating of the connectors may occur due to sagging of the board, etc. Mate connectors surely and then fix a spacer.

### | In Regards to Design Guideline |

To provide more information in regards to the usage of this product, we have prepared a detailed manual (ETAD-F0887-00). Please contact our sales representative if needed.

<b>HRS</b>	DRAWING NO. EDC-353553-20-00
	PART NO. FX23-60S-0.5SV(20)
	CODE NO. CL573-3203-5-20
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